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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)**?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details				
Product Status	Obsolete			
Architecture	MCU, FPGA			
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™			
Flash Size	-			
RAM Size	64KB			
Peripherals	DMA, POR, WDT			
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG			
Speed	700MHz			
Primary Attributes	FPGA - 350K Logic Elements			
Operating Temperature	0°C ~ 85°C (TJ)			
Package / Case	1517-BBGA, FCBGA			
Supplier Device Package	1517-FBGA, FC (40x40)			
Purchase URL	https://www.e-xfl.com/product-detail/intel/5asxbb3d4f40c6n			

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Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Advantage	Supporting Feature
Lowest system cost	 Requires as few as four power supplies to operate Available in thermal composite flip chip ball-grid array (BGA) packaging Includes innovative features such as Configuration via Protocol (CvP), partial reconfiguration, and design security

Summary of Arria V Features

Table 2: Summary of Features for Arria V Devices

Feature	Description
Technology	 TSMC's 28-nm process technology: Arria V GX, GT, SX, and ST—28-nm low power (28LP) process Arria V GZ—28-nm high performance (28HP) process Lowest static power in its class (less than 1.2 W for 500K logic elements (LEs) at 85°C junction under typical conditions) 0.85 V, 1.1 V, or 1.15 V core nominal voltage
Packaging	 Thermal composite flip chip BGA packaging Multiple device densities with identical package footprints for seamless migration between different device densities Leaded⁽¹⁾, lead-free (Pb-free), and RoHS-compliant options
High-performance FPGA fabric	 Enhanced 8-input ALM with four registers Improved routing architecture to reduce congestion and improve compilation time
Internal memory blocks	 M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC) (Arria V GX, GT, SX, and ST devices only) M20K—20-Kb memory blocks with hard ECC (Arria V GZ devices only) Memory logic array block (MLAB)-640-bit distributed LUTRAM where you can use up to 50% of the ALMs as MLAB memory

Send Feedback

 $^{^{(1)}}$ Contact Altera for availability.

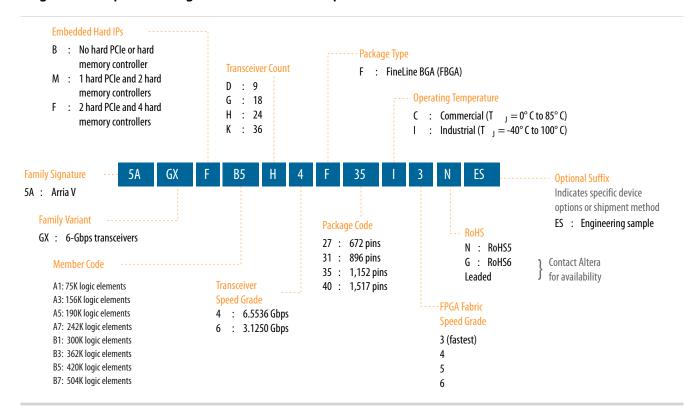
Feature	Description						
FPGA General- purpose I/Os (GPIOs)	 1.6 Gbps LVDS receiver and transmitter 800 MHz/1.6 Gbps external memory interface On-chip termination (OCT) 3.3 V support (2) 						
External Memory Interface	Memory interfaces with low latency: Hard memory controller-up to 1.066 Gbps Soft memory controller-up to 1.6 Gbps						
Low-power high- speed serial interface	 600 Mbps to 12.5 Gbps integrated transceiver speed Less than 105 mW per channel at 6 Gbps, less than 165 mW per channel at 10 Gbps, and less than 170 mW per channel at 12.5 Gbps Transmit pre-emphasis and receiver equalization Dynamic partial reconfiguration of individual channels Physical medium attachment (PMA) with soft PCS that supports 9.8304 Gbps CPRI (Arria V GT and ST only) PMA with hard PCS that supports up to 9.8 Gbps CPRI (Arria V GZ only) Hard PCS that supports 10GBASE-R and 10GBASE-KR (Arria V GZ only) 						
HPS (Arria V SX and ST devices only)	 Dual-core ARM Cortex-A9 MPCore processor—up to 1.05 GHz maximum frequency with support for symmetric and asymmetric multiprocessing Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, serial peripheral interface (SPI), I2C interface, and up to 85 HPS GPIO interfaces System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers On-chip RAM and boot ROM HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller ARM CoreSight™ JTAG debug access port, trace port, and on-chip trace storage 						



 $^{^{(2)}~{\}rm Arria~V~GZ}$ devices support 3.3 V with a 3.0 V ${\rm V}_{\rm CCIO}.$

Available Options

Figure 1: Sample Ordering Code and Available Options for Arria V GX Devices



Maximum Resources

Table 4: Maximum Resource Counts for Arria V GX Devices

Resource		Member Code							
neso	urce	A1	А3	A 5	A7	B1	В3	B5	В7
Logic I (LE) (F	Elements ζ)	75	156	190	242	300	362	420	504
ALM		28,302	58,900	71,698	91,680	113,208	136,880	158,491	190,240
Registe	er	113,208	235,600	286,792	366,720	452,832	547,520	633,964	760,960
Mem	M10K	8,000	10,510	11,800	13,660	15,100	17,260	20,540	24,140
ory (Kb)	MLAB	463	961	1,173	1,448	1,852	2,098	2,532	2,906
Variab precisi Block	le- on DSP	240	396	600	800	920	1,045	1,092	1,156
18 x 18 Multip		480	792	1,200	1,600	1,840	2,090	2,184	2,312
PLL		10	10	12	12	12	12	16	16



Resource		Member Code						
Neso	ui ce	C 3	C 7	D3	D7			
Transceiver	6 Gbps ⁽⁴⁾	3 (9)	6 (24)	6 (24)	6 (36)			
Transcerver	10 Gbps ⁽⁵⁾	4	12	12	20			
GPIO ⁽⁶⁾	GPIO ⁽⁶⁾		544	704	704			
LVDS	Transmitter	68	120	160	160			
LVD3	Receiver	80	136	176	176			
PCIe Hard IP Block		1	2	2	2			
Hard Memor	y Controller	2	4	4	4			

• High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

• Transceiver Architecture in Arria V Devices

Describes 10 Gbps channels usage conditions and SFF-8431 compliance requirements.

Package Plan

Table 7: Package Plan for Arria V GT Devices

Memb		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)		F1517 (40 mm)				
er Code		ХС	VR		ХС	VR		ХС	VR		2	KCVR
	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10- Gbps	GPIO	6- Gbps	10-Gbps
C3	336	3 (9)	4	416	3 (9)	4	_	_	_	_	_	_
C7	_	_	_	384	6 (18)	8	544	6 (24)	12	_	_	_
D3	_	_	_	384	6 (18)	8	544	6 (24)	12	704	6 (24)	12
D7	_	_	_	_	_	_	544	6 (24)	12	704	6 (36)	20

The 6-Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10-Gbps channels as three 6-Gbps channels—the total number of 6-Gbps channels are shown in brackets. For example, you can also configure the Arria V GT D7 device in the F1517 package with nine 6-Gbps



⁽⁴⁾ The 6 Gbps transceiver counts are for dedicated 6-Gbps channels. You can also configure any pair of 10 Gbps channels as three 6 Gbps channels-the total number of 6 Gbps channels are shown in brackets.

⁽⁵⁾ Chip-to-chip connections only. For 10 Gbps channel usage conditions, refer to the Transceiver Architecture in Arria V Devices chapter.

⁽⁶⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

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and eighteen 10-Gbps, twelve 6-Gbps and sixteen 10-Gbps, fifteen 6-Gbps and fourteen 10-Gbps, or up to thirty-six 6-Gbps with no 10-Gbps channels.

Arria V GZ

This section provides the available options, maximum resource counts, and package plan for the Arria V GZ devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Altera Product Selector.

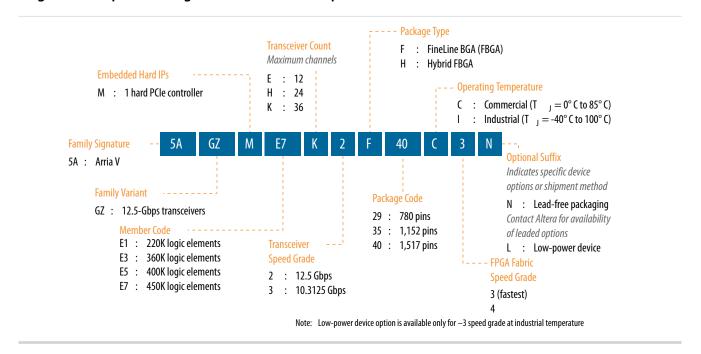
Related Information

Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 3: Sample Ordering Code and Available Options for Arria V GZ Devices



Maximum Resources

Table 8: Maximum Resource Counts for Arria V GZ Devices

Resource	Member Code						
nesource	E1	E 3	E 5	E 7			
Logic Elements (LE) (K)	220	360	400	450			
ALM	83,020	135,840	150,960	169,800			
Register	332,080	543,360	603,840	679,200			



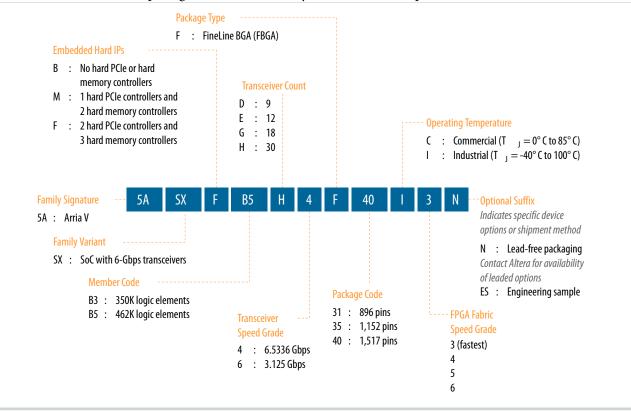
Altera Product Selector

Provides the latest information about Altera products.

Available Options

Figure 4: Sample Ordering Code and Available Options for Arria V SX Devices

The -3 FPGA fabric speed grade is available only for industrial temperature devices.



Maximum Resources

Table 10: Maximum Resource Counts for Arria V SX Devices

Poso	urce	Member Code			
neso	ruice	В3	B5		
Logic Elements (LE)	(K)	350	462		
ALM		132,075	174,340		
Register	Register		697,360		
Memory (Kb)	M10K	17,290	22,820		
Memory (Ro)	MLAB	2,014	2,658		
Variable-precision DSP Block		809	1,090		
18 x 18 Multiplier		1,618	2,180		



Poss	ource	Member Code			
neso	ruice	В3	B5		
FPGA PLL		14	14		
HPS PLL		3	3		
6 Gbps Transceiver		30	30		
FPGA GPIO ⁽⁸⁾		540	540		
HPS I/O		208	208		
LVDS	Transmitter	120	120		
LVDS	Receiver	136	136		
PCIe Hard IP Block	PCIe Hard IP Block		2		
FPGA Hard Memory	Controller	3	3		
HPS Hard Memory C	Controller	1	1		
ARM Cortex-A9 MP	Core Processor	Dual-core	Dual-core		

High-Speed Differential I/O Interfaces and DPA in Arria V Devices chapter, Arria V Device Handbook

Provides the number of LVDS channels in each device package.

Package Plan

Table 11: Package Plan for Arria V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

	F896		F1152			F1517			
Member Code	(31 mm)			(35 mm)				(40 mn	1)
Code	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
В3	250	208	12	385	208	18	540	208	30
B5	250	208	12	385	208	18	540	208	30

Arria V ST

This section provides the available options, maximum resource counts, and package plan for the Arria V ST devices.

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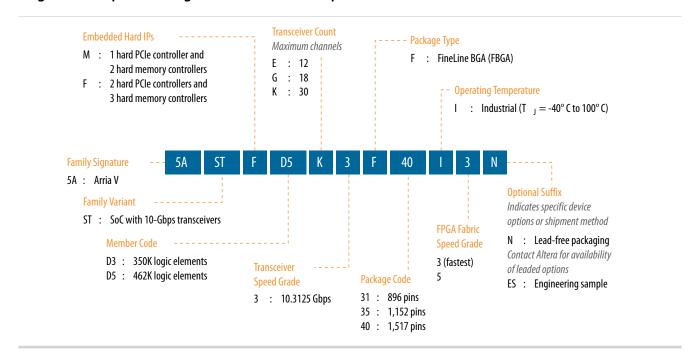
⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Quartus Prime software, the number of user I/Os includes transceiver I/Os.

Altera Product Selector

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Available Options

Figure 5: Sample Ordering Code and Available Options for Arria V ST Devices



Maximum Resources

Table 12: Maximum Resource Counts for Arria V ST Devices

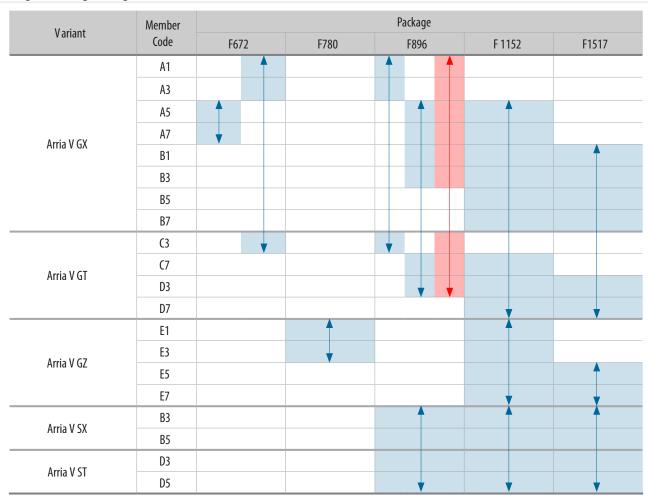
Reso	LINEO	Member Code			
Reso	ource	D3	D5		
Logic Elements (LE)	(K)	350	462		
ALM		132,075	174,340		
Register		528,300	697,360		
Memory (Kb)	M10K	17,290	22,820		
Memory (Rb)	MLAB	2,014	2,658		
Variable-precision D	SP Block	809	1,090		
18 x 18 Multiplier		1,618	2,180		
FPGA PLL	FPGA PLL		14		
HPS PLL		3	3		
Transceiver	6-Gbps	30	30		
114115001701	10-Gbps ⁽⁹⁾	16	16		



I/O Vertical Migration for Arria V Devices

Figure 6: Vertical Migration Capability Across Arria V Device Packages and Densities

The arrows indicate the vertical migration paths. Some packages have several migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



You can achieve the vertical migration shaded in red if you use only up to 320 GPIOs, up to nine 6 Gbps transceiver channels, and up to four 10 Gbps transceiver (for Arria V GT devices). This migration path is not shown in the Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the Pin Migration View window in the Quartus Prime software Pin Planner.

Note: Except for Arria V GX A5 and A7, and Arria V GT C7 devices, all other Arria V GX and GT devices require a specific power-up sequence. If you plan to migrate your design from Arria V GX A5 and A7, and Arria V GT C7 devices to other Arria V devices, your design must adhere to the same required power-up sequence.



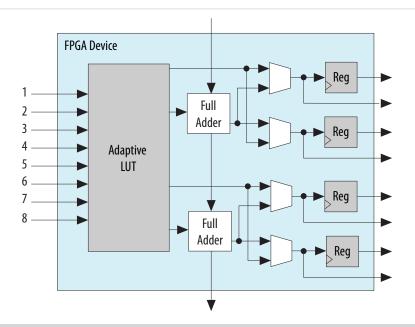
- Managing Device I/O Pins chapter, Quartus Prime Handbook Provides more information about vertical I/O migrations.
- Power Management in Arria V Devices
 Describes the power-up sequence required for Arria V GX and GT devices.

Adaptive Logic Module

Arria V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

Figure 7: ALM for Arria V Devices



You can configure up to 50% of the ALMs in the Arria V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Arria V Devices on page 20

Lists the embedded memory capacity for each device.



Variable-Precision DSP Block

Arria V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18, 27 x 27, and 36 x 36 bits natively
- A 64-bit accumulator
- Double accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Dynamic coefficients
- 18-bit internal coefficient register banks
- Enhanced independent multiplier operation
- Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Quartus Prime design software

Table 14: Variable-Precision DSP Block Configurations for Arria V Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resource
Low precision fixed point for video applications	Three 9 x 9	1
Medium precision fixed point in FIR filters	Two 18 x 18	1
FIR filters	Two 18 x 18 with accumulate	1
Single-precision floating- point implementations	One 27 x 27	1
Very high precision fixed point implementations	One 36 x 36	2

You can configure each DSP block during compilation as independent three 9 x 9, two 18 x 18, or one 27×27 multipliers. Using two DSP block resources, you can also configure a 36×36 multiplier for high-precision applications. With a dedicated 64 bit cascade bus, you can cascade multiple variable-precision DSP blocks to implement even higher precision DSP functions efficiently.



		M20K		M10K		MLAB		
Variant	Membe r Code	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	Total RAM Bit (Kb)
Arria V ST	D3	_	_	1,729	17,290	3223	2,014	19,304
71111a V 31	D5	_	_	2,282	22,820	4253	2,658	25,478

Embedded Memory Configurations

Table 17: Supported Embedded Memory Block Configurations for Arria V Devices

This table lists the maximum configurations supported for the embedded memory blocks. The information is applicable only to the single-port RAM and ROM modes.

Memory Block	Depth (bits)	Programmable Width	
MLAB	32	x16, x18, or x20	
MLAD	64 ⁽¹¹⁾	x10	
	512	x40	
	1K	x20	
M20K	2K	x10	
WIZOK	4K	x5	
	8K	x2	
	16K	x1	
	256	x40 or x32	
	512	x20 or x16	
M10K	1K	x10 or x8	
	2K	x5 or x4	
	4K	x2	
	8K	x1	

Clock Networks and PLL Clock Sources

650 MHz Arria V devices have 16 global clock networks capable of up to operation. The clock network architecture is based on Altera's global, quadrant, and peripheral clock structure. This clock structure is supported by dedicated clock input pins and fractional PLLs.

Note: To reduce power consumption, the Quartus Prime software identifies all unused sections of the clock network and powers them down.



⁽¹¹⁾ Available for Arria V GZ devices only.

PLL Features

The PLLs in the Arria V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Counter reconfiguration
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- Dynamic phase shift
- · Zero delay buffers

Fractional PLL

In addition to integer PLLs, the Arria V devices use a fractional PLL architecture. The devices have up to 16 PLLs, each with 18 output counters. One fractional PLL can use up to 18 output counters and two adjacent fractional PLLs share the 18 output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

Arria V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- $\bullet~$ LVDS output buffer with programmable differential output voltage (V $_{\rm OD}$) and programmable preemphasis
- On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Unused voltage reference (VREF) pins that can be configured as user I/Os (Arria V GX, GT, SX, and ST only)
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture



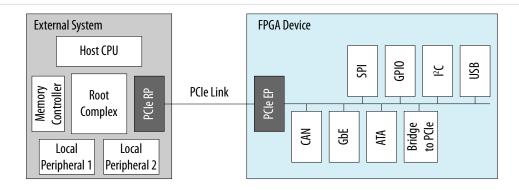
PCIe Gen1, Gen2, and Gen 3 Hard IP

Arria V devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen3, Gen 2, and Gen 1 end point and root port for up to x8 lane configuration.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 8: PCIe Multifunction for Arria V Devices



The Arria V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Arria V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Arria V device provides improved end-to-end datapath protection using ECC.

External Memory Interface

This section provides an overview of the external memory interface in Arria V devices.

Hard and Soft Memory Controllers

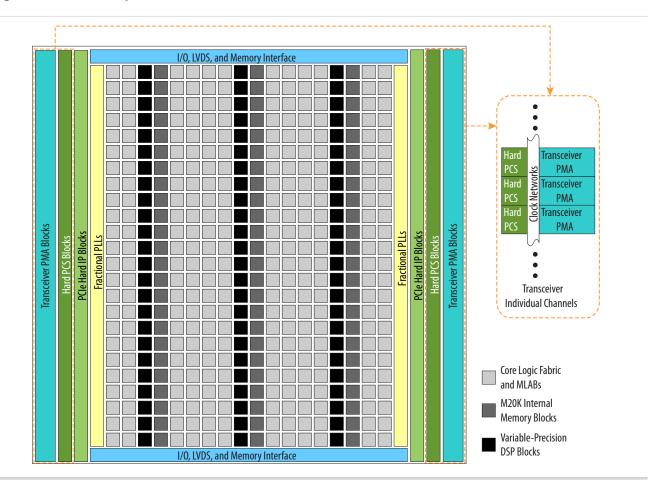
Arria V GX,GT, SX, and ST devices support up to four hard memory controllers for DDR3 and DDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Arria V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Arria V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices, QDR II+, QDR II, and DDR II+ SRAM devices, and RLDRAM II devices for maximum flexibility.

Note: DDR3 SDRAM leveling is supported only in Arria V GZ devices.



Figure 10: Device Chip Overview for Arria V GZ Devices





Features	Capability
PLL-based clock recovery	Superior jitter tolerance
Programmable serializer and deserializer (SERDES)	Flexible SERDES width
Equalization and pre-emphasis	 Arria V GX, GT, SX, and ST devices—Up to 14.37 dB of pre-emphasis and up to 4.7 dB of equalization Arria V GZ devices—4-tap pre-emphasis and de-emphasis
Ring oscillator transmit PLLs	611 Mbps to 10.3125 Gbps
LC oscillator ATX transmit PLLs (Arria V GZ devices only)	600 Mbps to 12.5 Gbps
Input reference clock range	27 MHz to 710 MHz
Transceiver dynamic reconfiguration	Allows the reconfiguration of a single channel without affecting the operation of other channels

PCS Features

The Arria V core logic connects to the PCS through an 8, 10, 16, 20, 32, 40, 64, 66, or 67 bit interface, depending on the transceiver data rate and protocol. Arria V devices contain PCS hard IP to support PCIe Gen1, Gen2, and Gen3, GbE, Serial RapidIO (SRIO), GPON, and CPRI.

All other standard and proprietary protocols within the following speed ranges are also supported:

- 611 Mbps to 6.5536 Gbps—supported through the custom double-width mode (up to 6.5536 Gbps) and custom single-width mode (up to 3.75 Gbps) of the transceiver PCS hard IP.
- 6.5536 Gbps to 10.3125 Gbps—supported through dedicated 80 or 64 bit interface that bypass the PCS hard IP and connects the PMA directly to the core logic. In Arria V GZ, this is supported in the transceiver PCS hard IP.

Table 21: Transceiver PCS Features for Arria V GX, GT, ST, and SX Devices

PCS Support ⁽¹³⁾	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Custom single- and double-width modes	0.611 to ~6.5536	Phase compensation FIFO	Word aligner8B/10B decoder
SRIO	1.25 to 6.25	Byte serializer 8B/10B encoder	Byte deserializer
Serial ATA	1.5, 3.0, 6.0	OB/10B chedder	Phase compensation FIFO



 $^{^{(13)}}$ Data rates above 6.5536 Gbps up to 10.3125 Gbps, such as 10GBASE-R, are supported through the soft PCS.

Table 22: Transceiver PCS Features for Arria V GZ Devices

Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
Custom PHY GPON	0.6 to 9.80 1.25 and 2.5	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering
Custom 10G PHY	9.98 to 12.5	TX FIFOGear boxBit-slip	RX FIFOGear box
PCIe Gen1 (x1, x2 x4, x8) PCIe Gen2 (x1, x2, x4, x8)	2.5 and 5.0	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding PIPE 2.0 interface to core logic 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer, Byte ordering PIPE 2.0 interface to core logic
PCIe Gen3 (x1, x2, x4, x8)	8.0	 Phase compensation FIFO 128B/130B encoder Scrambler Gear box Bit-slip 	 Block synchronization Rate match FIFO 128B/130B decoder Descrambler Phase compensation FIFO
10GbE	10.3125	TX FIFO64B/66B encoderScramblerGear box	 RX FIFO 64B/66B decoder Descrambler Block synchronization Gear box
Interlaken	3.125 to 12.5	 TX FIFO Frame generator CRC-32 generator Scrambler Disparity generator Gear box 	 RX FIFO Frame generator CRC-32 checker Frame decoder Descrambler Disparity checker Block synchronization Gear box



Protocol	Data Rates (Gbps)	Transmitter Data Path Features	Receiver Data Path Features
40GBASE-R Ethernet 100GBASE-R Ethernet	4 x 10.3125 10 x 10.3125	 TX FIFO 64B/66B encoder Scrambler Alignment marker insertion Gearbox Block stripper 	 RX FIFO 64B/66B decoder Descrambler Lane reorder Deskew Alignment marker lock Block synchronization Gear box Destripper
40G and 100G OTN	(4+1) x 11.3 (10+1) x 11.3	 TX FIFO Channel bonding Byte serializer	RX FIFOLane deskewByte deserializer
GbE	1.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding GbE state machine 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering GbE state machine
XAUI	3.125 to 4.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding XAUI state machine for bonding four channels 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering XAUI state machine for realigning four channels
SRIO	1.25 to 6.25	 Phase compensation FIFO Byte serializer 8B/10B encoder Bit-slip Channel bonding SRIO V2.1-compliant x2 and x4 channel bonding 	 Word aligner Deskew FIFO Rate match FIFO 8B/10B decoder Byte deserializer Byte ordering SRIO V2.1-compliant x2 and x4 deskew state machine



SoC with HPS

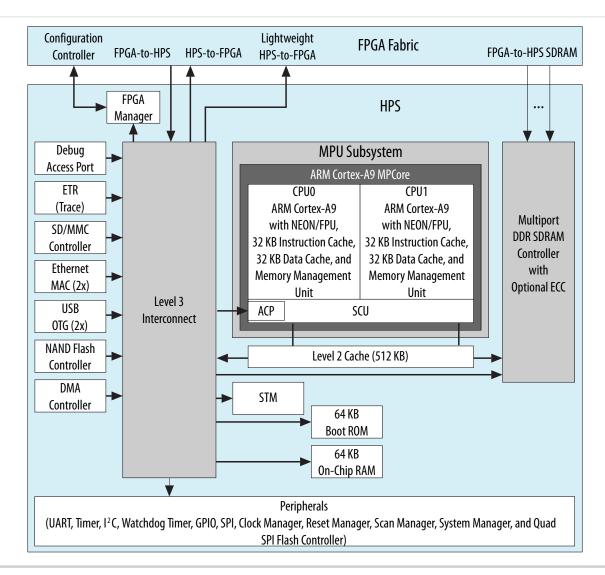
Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core ARM Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

Figure 12: HPS with Dual-Core ARM Cortex-A9 MPCore Processor





Date	Version	Changes
July 2012	2.1	 Added –I3 speed grade to Figure 1 for Arria V GX devices. Updated the 6-Gbps transceiver speed from 6.553 Gbps to 6.5536 Gbps in Figure 3 and Figure 1.
June 2012	2.0	 Restructured the document. Added the "Embedded Memory Capacity" and "Embedded Memory Configurations" sections. Added Table 1, Table 3, Table 12, Table 15, and Table 16. Updated Table 2, Table 4, Table 5, Table 6, Table 7, Table 8, Table 9, Table 10, Table 11, Table 13, Table 14, and Table 19. Updated Figure 1, Figure 2, Figure 3, Figure 4, and Figure 8. Updated the "FPGA Configuration and Processor Booting" and "Hardware and Software Development" sections. Text edits throughout the document.
February 2012	1.3	 Updated Table 1–7 and Table 1–8. Updated Figure 1–9 and Figure 1–10. Minor text edits.
December 2011	1.2	Minor text edits.
November 2011	1.1	 Updated Table 1–1, Table 1–2, Table 1–3, Table 1–4, Table 1–6, Table 1–7, Table 1–9, and Table 1–10. Added "SoC FPGA with HPS" section. Updated "Clock Networks and PLL Clock Sources" and "Ordering Information" sections. Updated Figure 1–5. Added Figure 1–6. Minor text edits.
August 2011	1.0	Initial release.

